



SPECIFICATION FOR APPROVAL

CUSTOMER	
NOMINAL FREQUENCY	10.000000 MHz
PRODUCT TYPE	TYPE FL 3.2x2.5 SEAM SEALED CRYSTAL
SPEC. NO. (P/N)	FL1000014Q
CUSTOMER P/N	
ISSUE DATE	November 1, 2017
VERSION	A

APPROVED	PREPARED	QA	
Brenda	Nikhi Lu	Dong Jang	

Diodes Incorporated

No.2, Ziqiang 5th Rd., Zhongli Industrial Park, Zhongli Dist., Taoyuan City 32063, Taiwan (R.O.C.)

TEL: 886-3-451-8888 FAX: 886-3-461-3865 https://www.diodes.com

- *Pb-free
- *RoHS Compliant
- *HF-Halogen Free
- *REACH Compliant
- *AEC-Q200 Compliant

E0-R-4-014 Rev. F

FL1000014Q

VER. A 1-Nov-17

VERSION HISTORY

Version No.	Version Date	Description	Notes
Α	Nov.1,2017	Initial Release	



E0-R-4-014 Rev. F

FL1000014Q

VER. A 1-Nov-17

ELECTRICAL SPECIFICATIONS

Item	Symbol	Specifications	Units	Notes
Nominal Frequency	Fn	10.000000	MHz	
Mode of Oscillation	MO	AT Cut-Fundamental		
Calibration Load Capacitance	CL	10	pF	
Calibration Tolerance	FL	±30	ppm	at 25°C±3°C
Operating Temperature Range	TR	-40 to +125	°C	
Frequency Stability (Frequency Deviation over the Operating Temperature Range)	F/T	±50	ppm	Reference to the Frequency at 25°C
Operating Drive Level		10	μW	
Maximum Drive Level		100	μW	
Equivalent Series Resistance	ESR	180	Ω	Max
Shunt Capacitance	C0	5	pF	Max
Aging at 25°C		±3	ppm	Max, 1st year
Storage Temperature		-55 to +125	°C	
Insulation Resistance		500	МΩ	Min

* This product doesn't include harmful substance that stipulated by SONY SS-00259 Level 1 and S-AT2-001 Level 1 standard. RoHS Compliant (Pb - Free).



FL1000014Q

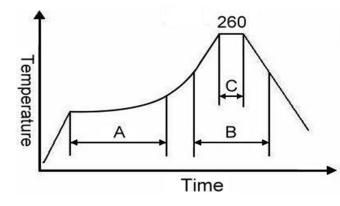
VER. A 1-Nov-17

AEC-Q200 RELIABILITY TEST SPECIFICATIONS:

- 1. Initial
- 1.1 Physical Dimensions: JESD22, Method JB1-100
- 1.2 External Visual: MIL-STD-883, Method 2009
- 1.3 Freq. Vs. Temperature: Per Specification/Datasheet
- 2. Mechanical
- 2.1 Mechanical Shock: MIL-STD-202 Method 213
- 2.2 Vibration: MIL-STD-202 Method 204
- 2.3 Solderability: J-STD-002
- 2.4 Board Flex: AEC Q200-005
- 2.5 Terminal Strength (SMD): AEC Q200-006
- 3.Environmental
- 3.1 Temp Cycle: JESD22, Method JA-104
- 3.2 Resistance to Solder Heat: MIL-STD-202 Method 210
- 3.3 High Temperature Operating Life: MIL-STD-202, Method 108
- 3.4 High Temp Exposure: MIL-STD-202, Method 108
- 3.5 High Temp & High Humidity: MIL-STD-202, Method 103
- 3.6 Thermal Shock: MIL-STD-202, Method 107

SUGGESTED IR REFLOW PROFILE

*As per IPC-JEDEC J-STD-020D



N	•	·	

	Stage	Temperature	Time
Α	Preheat	150~200°C	60~120 Sec
В	Primary Heat	217°C	60~150 Sec
С	Peak	260°C	10 Sec

Page 2

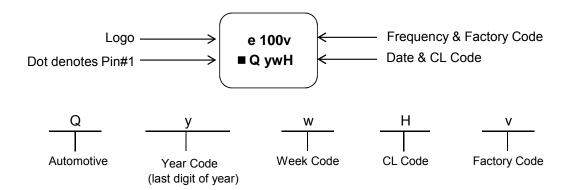
E0-R-4-014 Rev. F



FL1000014Q

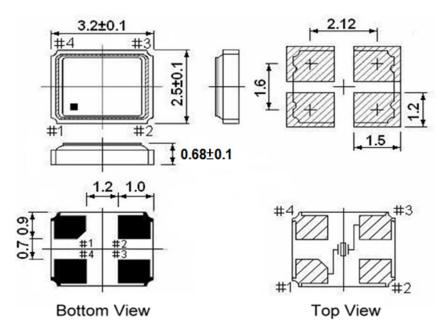
VER. A 1-Nov-17

MARKING



MECHANICAL DRAWINGS (Scale: None. Dimensions are in mm.)

Recommended Land Pattern



** Recommended - Pin 1 & 3 : CRYSTAL Pin 2 & 4 : GND

Notes:

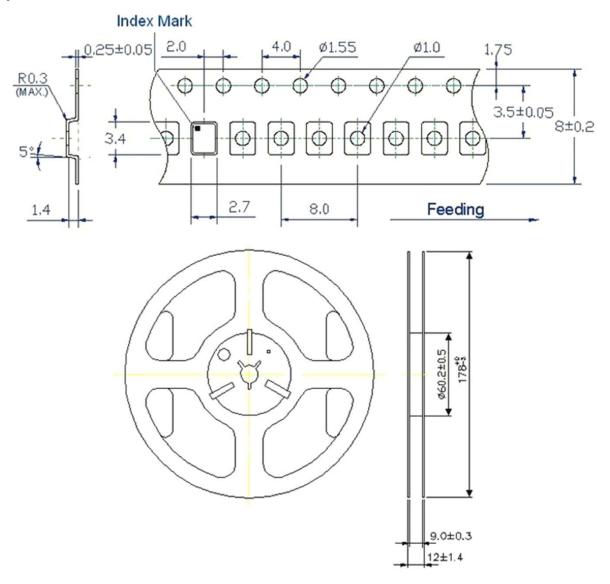
- Package drawings are for reference only, and the appearances of objects may vary.
 Actual packages are based on the real product.
- 2. The marking dot denotes Pin#1.
- 3. The position and shape of the chamfer pin may vary and are based on the real product.



FL1000014Q

VER. A 1-Nov-17

Tape & Reel



- 1. 230mm minimum leafer which consist of carrier and/or tape followed by a minimum of 160mm of empty carrier tape sealed with cover tape.
- 2. 160mm minimum trailer of empty carrier tape sealed with cover tape.

